

# SOT1799-5

CFM6F, ceramic flange mount flat package; 6 terminals; 5.36 mm pitch, 9.78 mm x 20.58 mm x 3.75 mm body

10 July 2018

Package information

## 1 Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	CFM6F
<b>Package style descriptive code</b>	CFMF (ceramic flange mount flat)
<b>Package body material type</b>	C (ceramic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	30-05-2018
<b>Manufacturer package code</b>	98ASA01118D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	9.7	9.78	9.86	mm
package width	20.45	20.58	20.7	mm
package height	3.18	3.75	4.32	mm
nominal pitch	-	5.36	-	mm
actual quantity of termination	-	6	-	



2 Package outline

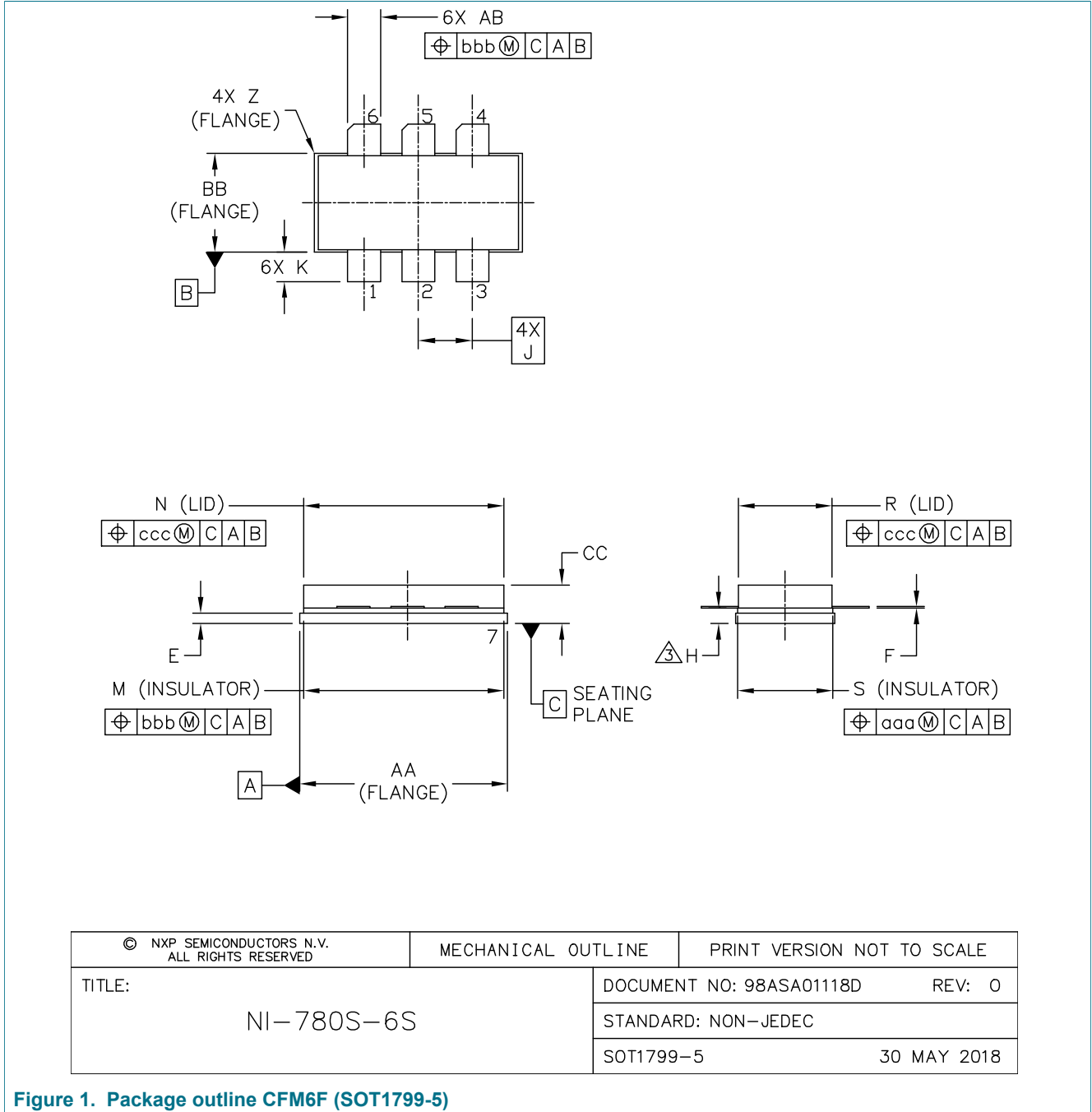


Figure 1. Package outline CFM6F (SOT1799-5)

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NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1994.

2. CONTROLLING DIMENSION: INCH.

3. DIMENSION H IS MEASURED .030 INCH (0.762 MM) AWAY FROM FLANGE PARALLEL TO DATUM B TO CLEAR EPOXY FLOW OUT.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
AA	.805	.815	20.45	20.70	Z	R.000	R.040	R0.00	R1.02
BB	.382	.388	9.70	9.86	AB	.124	.134	3.15	3.40
CC	.125	.170	3.18	4.32	aaa	.005		0.13	
E	.035	.045	0.89	1.14	bbb	.010		0.25	
F	.003	.006	0.08	0.15	ccc	.015		0.38	
H	.057	.067	1.45	1.70					
J	.211 BSC		5.36 BSC						
K	.0995	.1295	2.53	3.29					
M	.774	.786	19.66	19.96					
N	.772	.788	19.61	20.02					
R	.365	.375	9.27	9.53					
S	.365	.375	9.27	9.53					
© NXP SEMICONDUCTORS N. V. ALL RIGHTS RESERVED			MECHANICAL OUTLINE			PRINT VERSION NOT TO SCALE			
TITLE:  NI-780S-6S					DOCUMENT NO: 98ASA01118D      REV: 0				
					STANDARD: NON-JEDEC				
					SOT1799-5		30 MAY 2018		

Figure 2. Package outline note CFM6F (SOT1799-5)

### 3 Legal information

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